

Accelerating Al with Real-World CXL Platforms

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Agenda

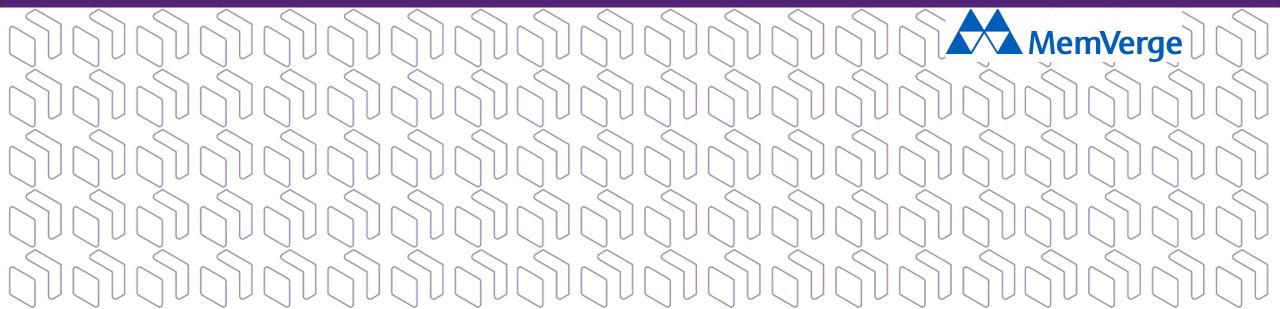
- ◆The CXL Advantage for Real-World AI Workloads
- ◆ Boost Your AI Workload Performance Using CXL Memory
- → Deploying CXL in Next Generation AI/ML Systems





The CXL Advantage for Real-World AI Workloads

Steve Scargall



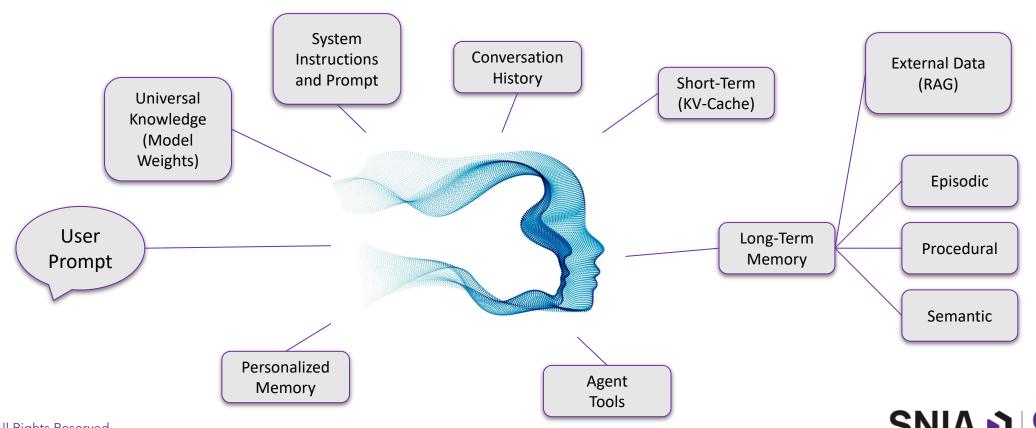
Accelerating AI: CXL and High-Capacity Memory Solutions

- In the rapidly evolving landscape of Artificial Intelligence, the demand for greater memory capacity and bandwidth is insatiable.
- Compute Express Link (CXL) is emerging as a pivotal technology in 2025, directly addressing the memory bottlenecks and capacity that can throttle AI workloads.



The Context Engineering Era: The CXL Opportunity

Context engineering is the practice of designing systems that provide large language models (LLMs) with the necessary information and tools to perform tasks effectively. It goes beyond simple prompt engineering, which focuses on crafting specific instructions. Instead, context engineering involves assembling a comprehensive context that includes:





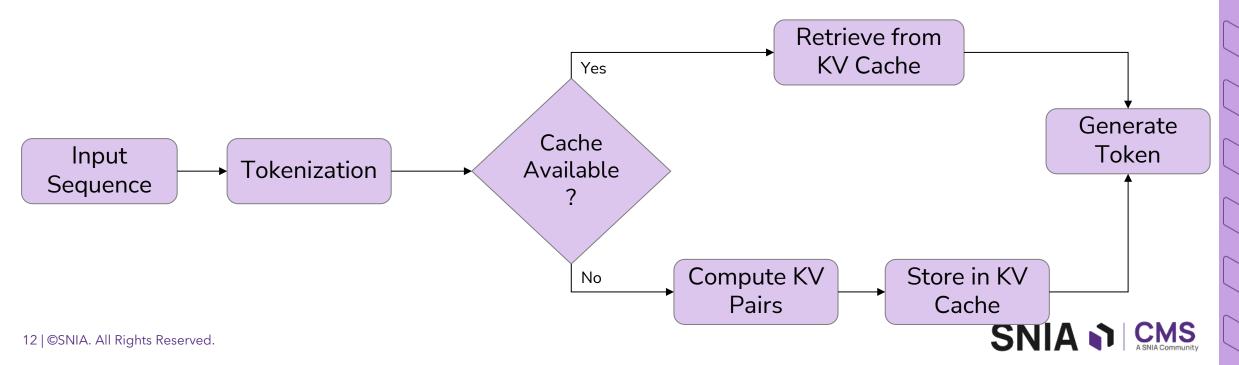
KV-Cache: The Heart of LLM Inferencing



The Hidden Cost of Long Context: KV Cache

The KV-Cache Problem:

- Large Language Models (LLMs) rely on a Key-Value (KV) Cache to avoid re-computing attention for previous tokens.
- For long prompts or conversations, this KV Cache can grow to hundreds of gigabytes, consuming precious and expensive GPU High-Bandwidth Memory (HBM).
- This "memory tax" limits the number of users (batch size) a single GPU can serve, creating a throughput bottleneck.



How Much GPU Memory Do You Need for Efficient LLM Serving?

Total Required GPU Memory = (Model Weights) + (KV Cache) + (Activations) + (Overhead)

The main components contributing to it are:

- **Memory for Model Weights:** (Model Size in Parameters) x (Bytes per Parameter)
- Memory for KV Cache: (Batch Size) x (Sequence Length) x (2 tensors [K,V]) x (Num Layers) x (Hidden Size) x (Bytes per Parameter)
- Memory for Activations: This is temporary memory used during the model's forward pass, dependent on model architecture and sequence length.
- System & Framework Overhead: This is a typically fixed amount of memory reserved for CUDA kernels, the serving framework, and other system processes.

Note: Model Weights, Activations, and Overhead are fixed values. The KV-Cache is variable.



GPU Memory Requirements: Scaling Users

Scenario Assumptions

- Model: 7B Parameter LLM
- Precision: FP16 (2 bytes/param)
- Context Length: 8,192 tokens
- Architecture: 32 layers, 4096 hidden size

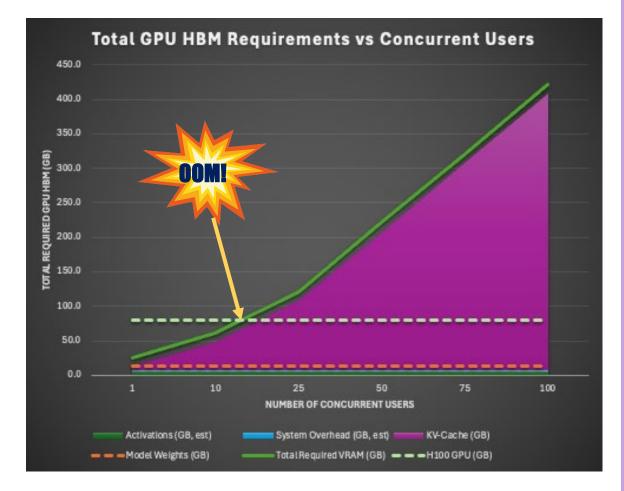
Static Memory Base

~21GB

The fixed cost of (Model Weights (~16GB)) + (Activations + Overhead (~5GB)).

Max Users on a single NVIDIA H100 with KV-Cache up to ~16

100 users requires ~6 x NVIDIA H100 (80GB)



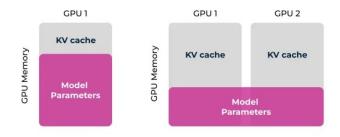
Key Takeaways:

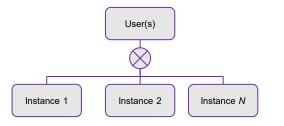
- **KV Cache Dominates:** The memory required for the KV Cache quickly surpasses the size of the model weights, especially with a long context window and multiple users.
- The Physical GPU Memory Limit: Memory offloading and expansion strategies are critical for scaling.



Possible Solutions

- Buy more GPUs (\$\$\$\$)
 - Pro: Increases HBM Capacity
 - o Cons:
 - Expensive approach to increase HBM
 - Wasted GPU Tensor Compute Resources (idle)
- Quantize the Model
 - O Pro: Reduces Model Parameters Memory Requirement
 - Cons: Reduces Accuracy
- Run multiple instances and route user sessions
 - Pro: Scale-out solution to handle user sessions
 - Con: Requires more Servers/Instances (power/cooling...)
- Offload KV-Caches (Memory Tiering)
 - Pro: Use the capacity and bandwidth of DRAM + CXL
 - Con: Higher Latency for warm memory access (relative to HBM)

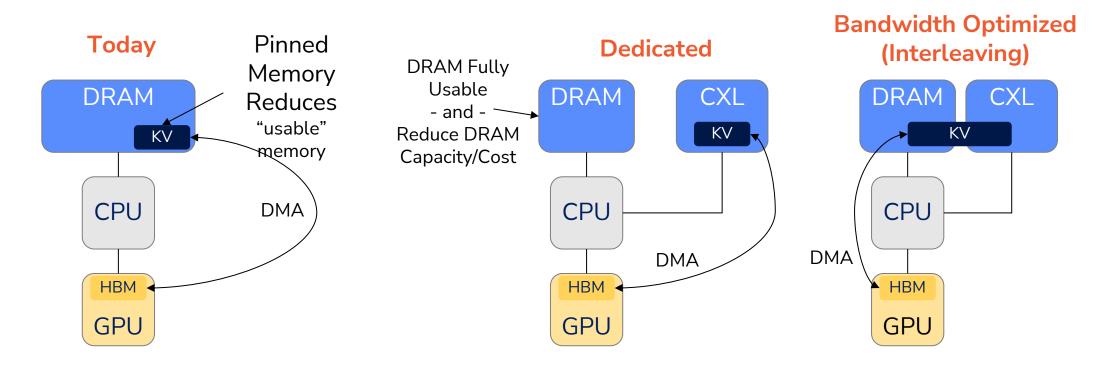






KV Cache Offloading

- Use DRAM & CXL memory as a vast, secondary tier for the KV Cache.
- The CXL-to-GPU interconnect offers low latency and high bandwidth, making it a perfect fit for this "warm" tier of data.



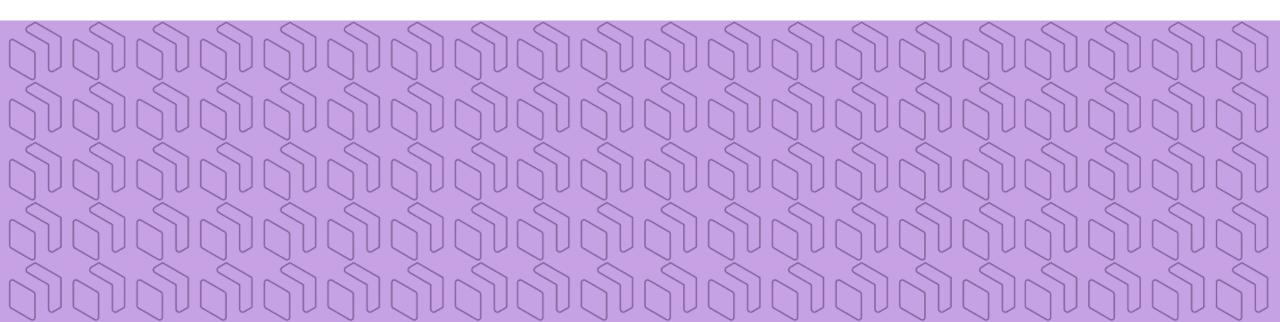
KV Cache Offload Benefits

- Massively Increased Batch Size: Freeing up GPU HBM allows for significantly more concurrent users.
- Reduced TCO:
 - Serve larger models with fewer, more efficiently utilized GPUs.
 - Reduce the number of GPUs
- Enable Future Models: Provides a path to serve future models with even larger context windows.





Improving Distributed LLM Inference @Scale



Distributed Inferencing

The Problem & Challenges @ Scale:

- Scaling inference for generative AI and reasoning models presents complex challenges in three key areas: performance, correctness, and efficiency.
 - **GPU underutilization**: Traditional monolithic inference pipelines often leave GPUs idle due to the imbalance between prefill and decode stages.
 - **Expensive KV cache re-computation**: When requests aren't efficiently routed, KV caches often get flushed and recomputed, leading to wasted computation cycles and increased latency.
 - **Memory bottlenecks**: Large-scale inference workloads demand extensive KV cache storage, which can quickly overwhelm GPU memory capacity.
 - *Inefficient data transfer*: Distributed inference workloads introduce unique and highly dynamic communication patterns that differ fundamentally from training.



Distributed Inferencing

The Solution:

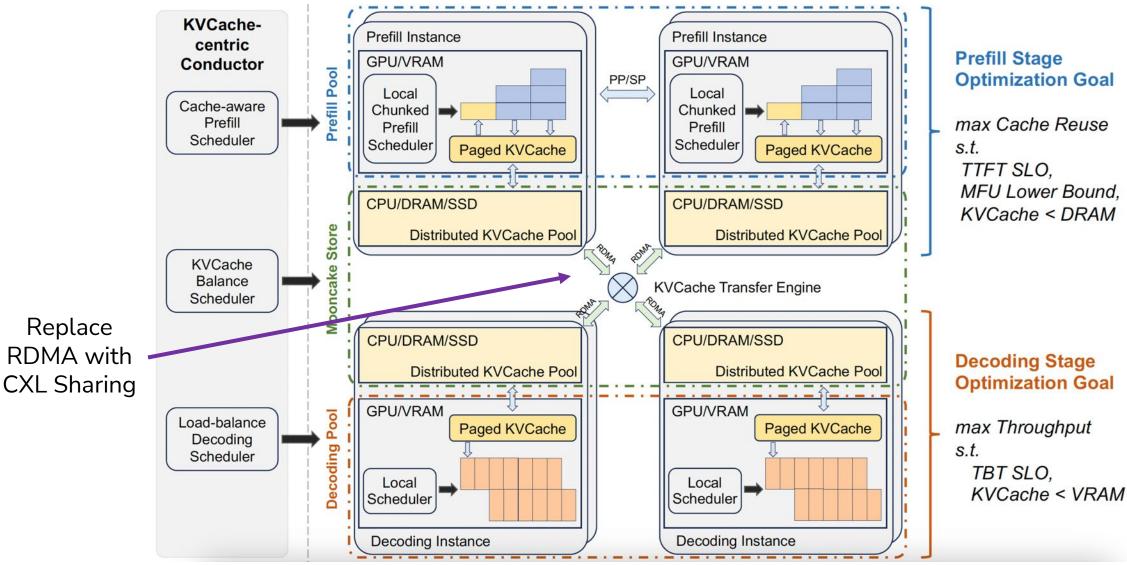
- Leading-edge serving platforms, such as NVIDIA Dynamo, LLM-D, VLLM, and Mooncake, are built on the principle of disaggregation.
- For efficient global memory management at scale, the platforms strategically store and evict KV caches across multiple memory tiers—GPU, CPU, SSD, and object storage - enhancing both timeto-first-token and overall throughput.
- CXL Fabrics can facilitate high-throughput, low-latency, and efficient transfer and interconnect between inference instances, leading to higher optimization and throughput of tokens per second.



NVIDIA Dynamo & NIXL

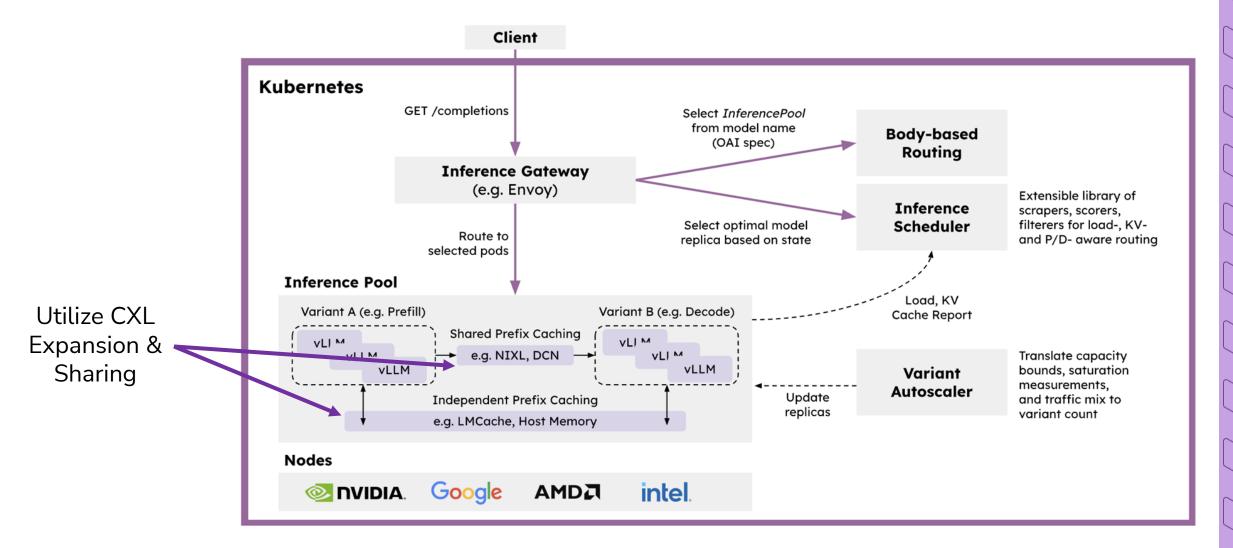


Mooncake Architecture

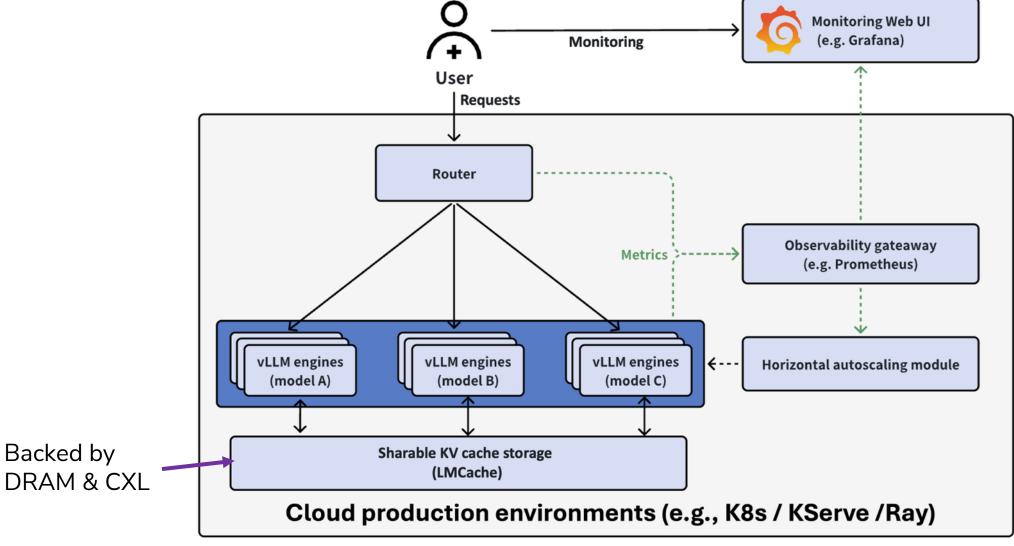




LLM-D



VLLM Architecture



Source: https://docs.vllm.ai/projects/production-stack/en/latest/getting_started/installation.html



Takeaways

- Context Engineering is happening now, requiring high memory capacity and bandwidth - A great opportunity for CXL.
- KV-Cache dominates the GPU memory requirements @ scale
- Offloading the KV-Cache and/or Model Parameters is an efficient approach to scaling
- With modifications, existing LLM Inference frameworks can adopt CXL Expansion and Sharing



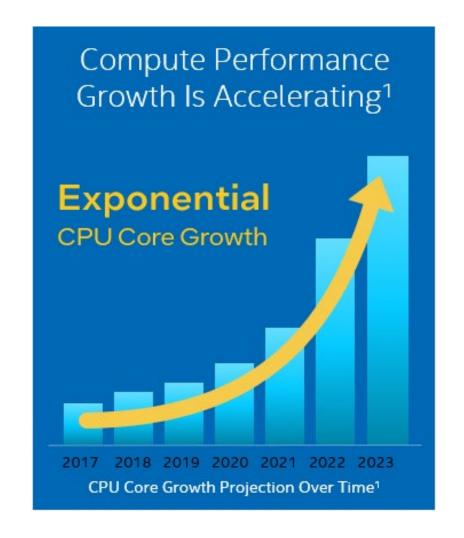


Boost Your Al Workload Performance Using CXL Memory

Anil Godbole

Compute Core Count Keeps Increasing

- Needed to keep up with memory intensive workloads
- **⋄** W/L Examples
 - Virtualized servers
 - In-memory data bases
 - Al/ML
 - Many others...





Value Prop of CXL-attached Memory

Increased Memory Capacity

Improve processor perf

Reduced SSD accesses

Benefitting Workloads

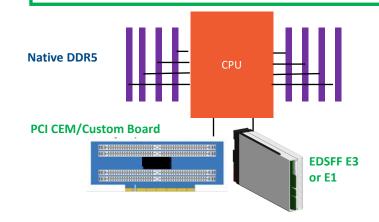
- Virtualized Servers
- In-memory Databases
- AI / ML
- HPC (High Perf Computing)
- Media (CDN, Video 8K)
- Medical (Genomics)

Increased Memory Bandwidth

Improve processor's memory bandwidth using address interleaving

Benefitting Workloads

- AI/ML
- HPC
- Non-relational Databases



Lower Memory TCO

Avoid expensive 3DS DIMMs

- Use standard DIMM capacities for native & CXL
- Use lower-cost memory media on CXL
 - DDR4

Memory Pooling

 For optimal provision of local DRAM on servers



TCO Savings Examples with CXL Memory Avoid high-cost DIMMs

- ↑ 128GB and 256GB DIMMs have high price premiums
- OCXL add-in cards with DIMM slots provide more total channels per socket → same system capacity with lower priced DIMMs

Memory per socket	Socket- attached DIMMs only	With CXL	Memory TCO Savings*
1TB	8x 128GB (1DPC)	8x 64GB + 8x 64GB on CXL	24%
2TB	16x 128GB	16x 64GB + 16x 64GB on CXL	27%
4TB	16x 256GB	16x 128GB + 16x 128GB on CXL	16%

^{*}TCO savings based on Intel modeling using projected DIMM and CXL pricing for 2025

*TCO savings even more if DDR4 RDIMMs are reused using AICs

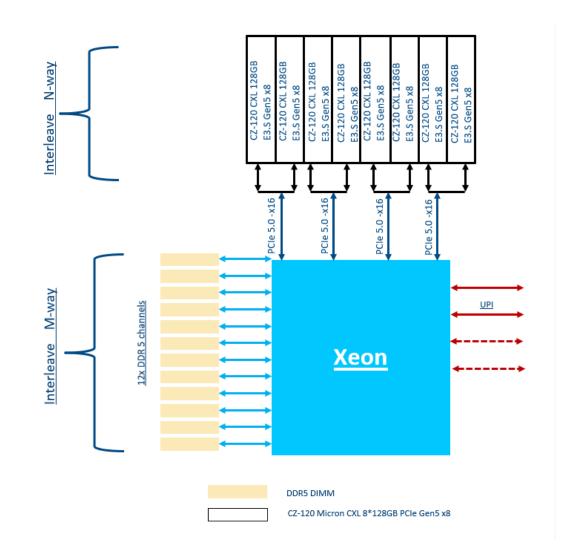
Use CXL-attached DIMMs to achieve high system memory capacity:

Avoid expensive high-capacity DIMMs



S/W-Assisted B/W-Weighted Memory Interleaving

- SW (Hypervisor/OS/App) responsible for tiering & interleaving*
- Systems boots as two-tier memory (Near & Far)
- S/w 'stripes' pages between native & CXL memory
 - Uses page-table entries to assign physical addresses to virtual address pages
- Page-striping ratio ('M:N')
 - No. of pages in native DRAM / No. of pages in CXL memory)
 - Typically based on ratio of native DRAM memory wrt CXL memory b/w
 - But completely flexible for S/W to choose
- No page movement involved
 - Pages remain 'pinned' in their respective memories





^{*}Upstreamed to Linux with Kernel v6.9 & beyond

Bandwidth Expansion with DDR5 + CXL Memory

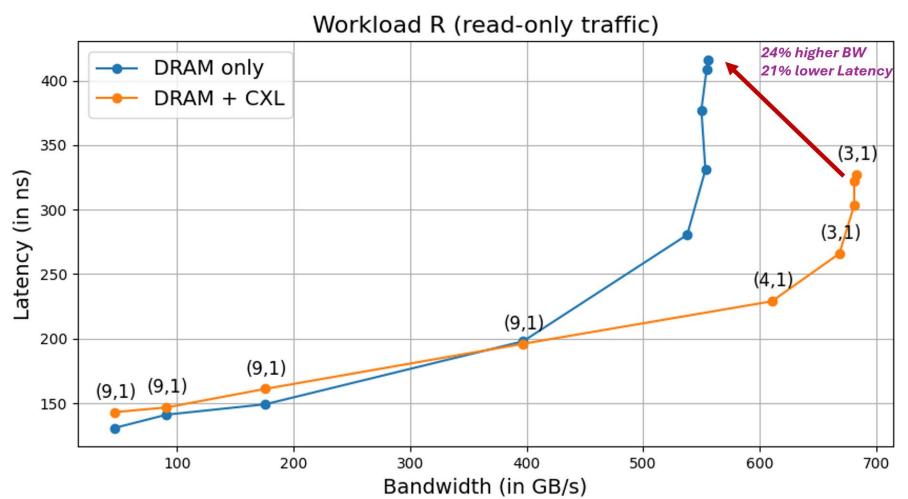
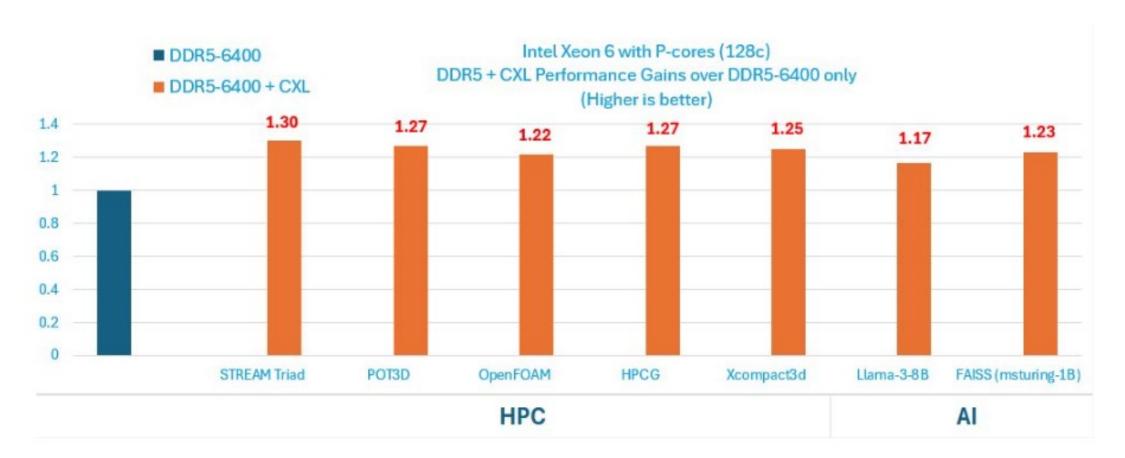


Chart with Intel Xeon 6900 with Micron DDR5 DIMMs & CXL CZ-120 modules

Interleaving weights given by (M,N) pairs



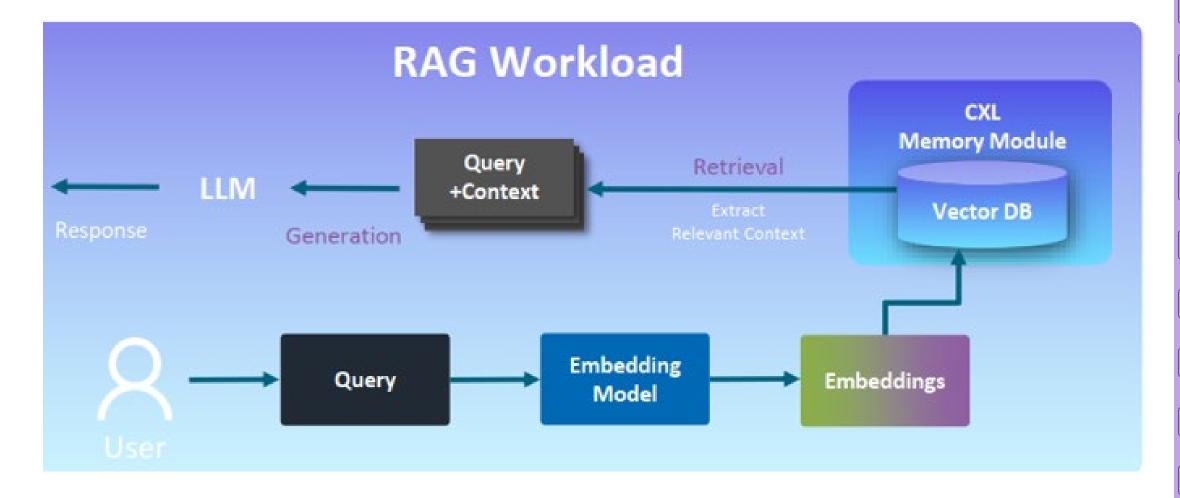
HPC W/Ls Performance Examples



https://community.intel.com/t5/Blogs/Tech-Innovation/Data-Center/Improve-your-HPC-and-AI-workload-performance-by-increasing/post/1647882



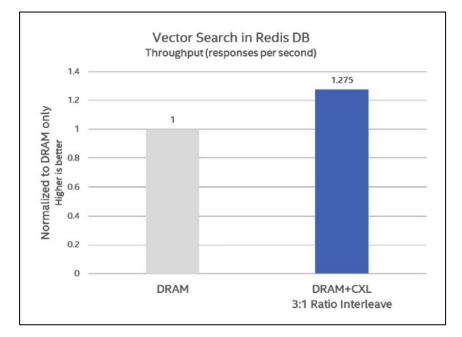
RAG (Retrieval Augmented Generation) based Al

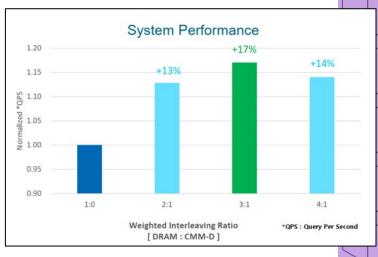




In-Memory RAG Database Performance Gains







23%+ for FAISS Vector Db

CPU: Intel Xeon-6 6900 w/ 128 cores

CXL: Micron CZ122 128GB

27%+ for Redis Vector Db

CPU: Intel Xeon-6 6787P w/ 86 cores

CXL: 2x x16 Astera Leo D5 DRAM: Hynix 64GB RDIMMs

17% Put Perf for Milvus DB CPU: Intel Xeon-6 6767 w/ 64c CXL: Samsung CMM-D 256GB



Intel CXL Enablement Roadmap

4th & 5th Gen Intel® Xeon® Gen4 (SPR) / Gen5(EMR) Eagle Stream Platform)

- Supports CXL v1.1 spec
- Leadership in CXL ecosystem enablement

Gen Intel® Xeon® CPU
Gen6 (GNR, SRF)
Birch Stream Platform*

- Supports CXL v2.0 spec
- Enhanced support for CXL Memory

Future Gen Intel® Xeon® CPU

Support for CXL v3.x

Intel Xeon Roadmap Fully Aligned with CXL Roadmap



Summary

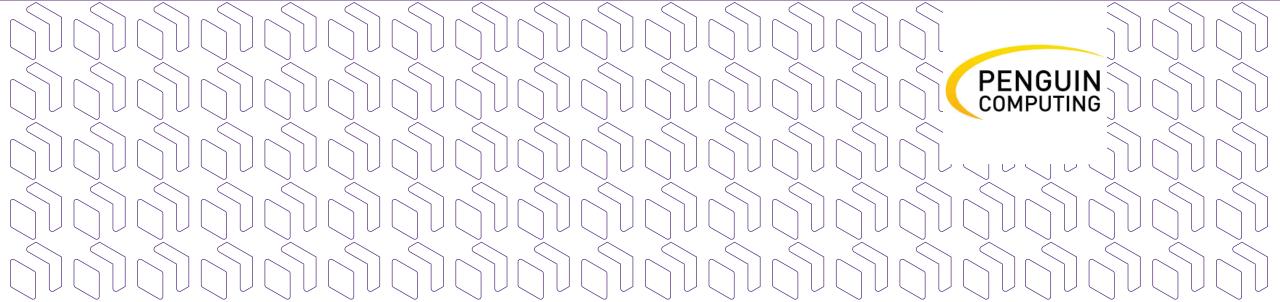
- CPUs will play a big role in the AI revolution in the coming years
- There are many AI workloads like RAG, small LLM inferencing where CPUs can do the job more economically
 - Without needing a GPU
 - With CXL memory giving a boost
- Intel Xeon 6900/6700/6500 CPUs and coupled with CXL ecosystem of both h/w devices & s/w is available for your Al workloads





Deploying CXL in Next Generation Al/ML Systems

Andy Mills

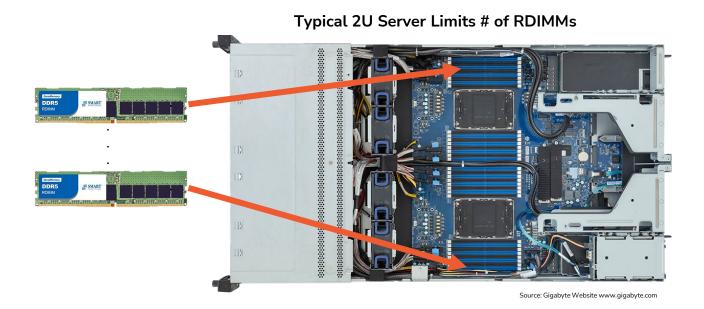


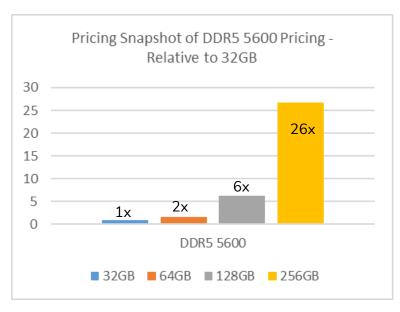
Scaling Memory in Al Servers

- Challenges deploying large memory footprints today
 - ♠ Limit to number of RDIMMs per CPU = capacity limit
 - ♠ Limit to HBM directly addressable by GPUs = capacity limit
 - ♠ Expansion by networking multiple CPUs or GPUs together with a high-performance network = capacity gains, new network performance limits
 - More CPUs + GPUs + network hardware = significantly higher power consumption
- Industry needs to solve for higher performance, higher capacity memory per CPU and GPU, while minimizing power consumption, heat generation, etc



Scaling Memory Today - Single Server Unit





Non-Linear Price Scaling of RDIMMs

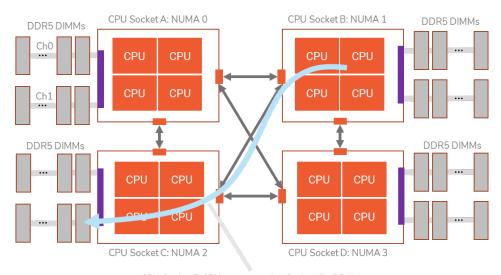
Maximum Memory Capacity of Mainstream 2U 2-socket Servers

	AMD TURIN (12 PER CPU, 1DPC)	INTEL GRANITE RAPIDS SP (16 PER CPU, 2DPC)
64GB RDIMMS	1.536TB	2.048TB
96GB RDIMMS	2.304TB	3.072TB
128GB RDIMMS	3.072TB	4.096TB
256GB RDIMMS	6.144TB	8.192TB



Traditional Methods for Overcoming CPU Memory Limits

Increase number of CPUs e.g. 4-socket



CPU Socket B CPU core accessing Socket C's DRAM

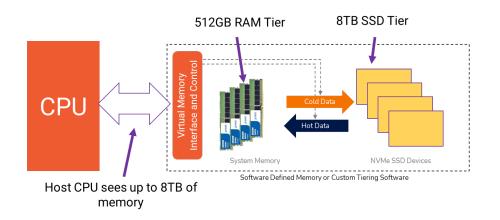
Pro:

- Doubles size of memory via CPU expansion
- NUMA allows access to all memory via high-speed CPU interconnects

Con:

Expensive if CPUs are simply being used a "memory controllers"

Utilize Software Defined Memory Tiering with SSDs



Pro:

- Significantly increases size of virtual memory
- SSDs provide a low-cost expansion method

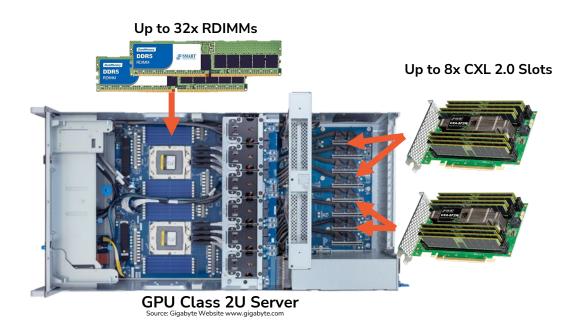
Con:

- Heavy performance tax if/when data hits SSD "memory tier"
- SSD tier runs at up to 1000x slower than main memory tier

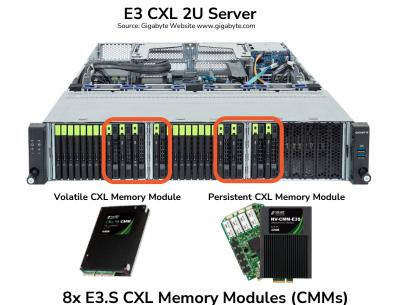


Scaling Server Memory Using CXL AICs

24.576TB



22.538TB



8.192TB

INTEL GRANITE RAPIDS INTEL GRANITE RAPIDS AMD TURIN AMD TURIN SP SP 24 RDIMMS + 64 CXL RDIMMS 32 RDIMMS + 64 CXL RDIMMS 32 RDIMMS + 8 CXL CMMS 24 RDIMMS + 8 CXL CMMS 64GB RDIMMS 5.632TB 64GB RDIMMS 6.144TB 2.048TB 2.560TB 96GB RDIMMS 96GB RDIMMS 8.448TB 3.072TB 3.840TB 9.216TB 128GB RDIMMS 5.120TB 128GB RDIMMS 4.096TB 11.264TB 12.288TB

256GB RDIMMS



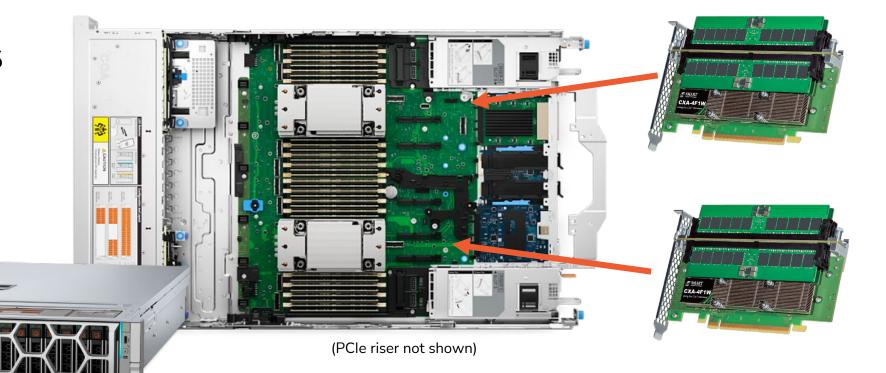
10.240TB

256GB RDIMMS

OEM Server Adoption

Dell now offering CXL enabled servers with Dell CXL add-in-cards

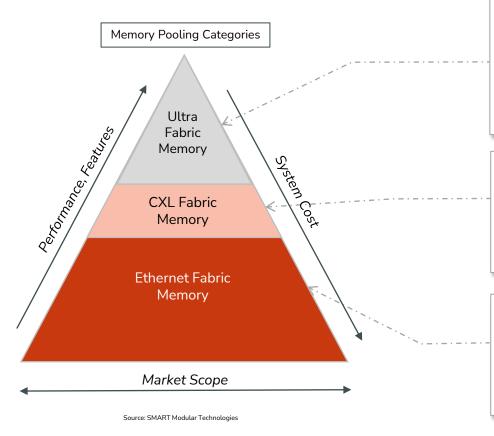
- PowerEdge R7725 (AMD EPYC™)
- PowerEdge R770 (Intel Xeon®)



Source: Dell Website (www.dell.com)



Memory Pooling Product Segments



Ultra Fabric Memory (UFM)

- HBM and DDR5 Memory Types
- CPU and XPU/GPU attach options
- CXL 3.1, HBM, memory fabric native protocols
- 800GB/s-1.6TB/s per port, low latency
- Custom all-optics (Silicon Photonics) Cabling and Switches, with Future Standards path to UALink/other Fabrics

CXL Fabric Memory (CFM)

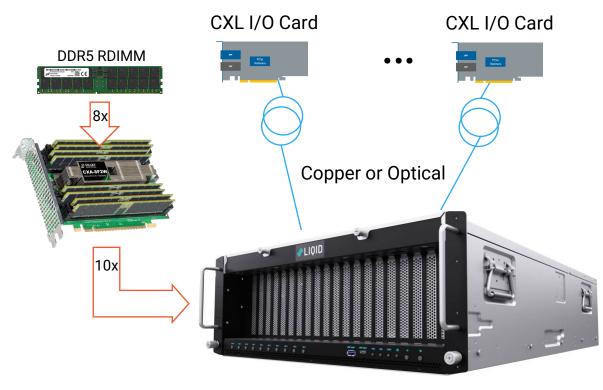
- DDR5 Pooling
- CPU attach only
- CXL 2.0/3.1 protocol
- 64-128GB/s per port, standard latency
- Standards Based PCIe SIG Cabling and Switches

Ethernet Fabric Memory (EFM)

- DDR5 Pooling
- Ethernet attached
- Memory as a service, CXL Over Ethernet
- Up to 800Gb/s per port, high latency
- Standard Based Ethernet Cabling and Switches



First Generation CXL Fabric Pooling



Up to 80 RDIMMs

For RAG Applications, sharing Vector dBases between CPUs helps reduce fragmentation overhead

⋄ Features

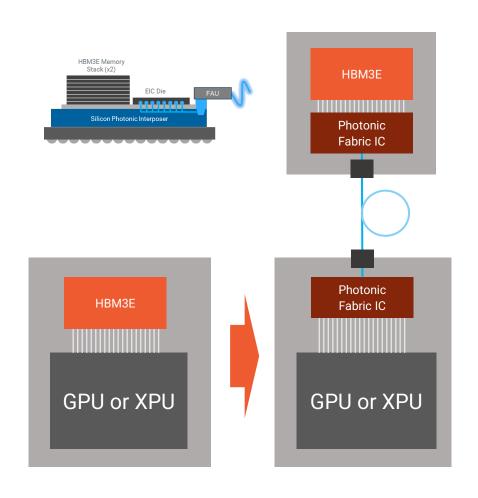
- Memory pooling appliance allows up to 10 CXL AICs to be housed in one unit
- Support up to 80 DDR5 RDIMMs (or 120 DDR4 RDIMMs) in one chassis
- Eventually will support other PCIe peripherals e.g. GPU, FPGA or NIC
- Share memory pool with up to 5 servers via disaggregation management software
- Expandable with dedicated switch units

N Benefits

- Host server only needs to use a single PCIe/CXL slot
- Unit may be serviced and memory upgraded/added/removed without powering off servers



The Rise of Silicon Photonic Memory

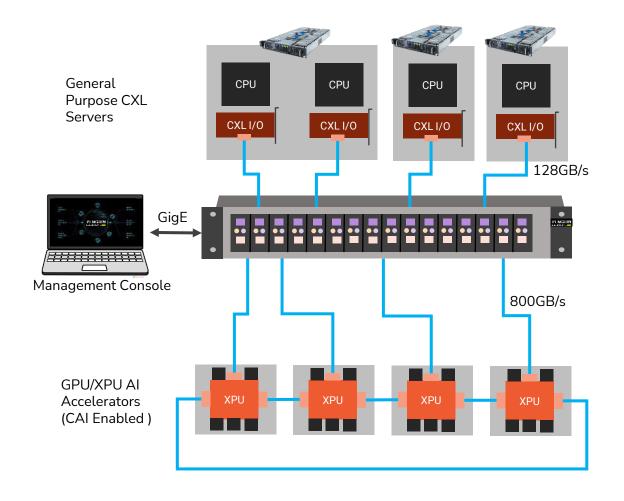


- Silicon Photonics Avoids the Beachfront problem and allows serializing of HBM data streams over optical channels and fiber
- → HBM3 uses 1024 data signals. HBM4 discussing 2048 data signals which takes up even more silicon "beachfront"
- Moving to serial attached memory with on-chip optics allows HBM memory to be located "off chiplet" and opens the path to GPU-CPU sharing architectures



A Peek at the Future

Optical HBM Based Memory Pooling Appliance



- Share HBM Class Memory between multiple Servers and Custom XPU AI Accelerators
 - Significant reductions in data movement hence power
- Memory Supported
 - Up to 32TB DDR5 RDIMMs
 - Up to 1TB HBM3E
- Memory Access Modes
 - HBM Direct Mode
 - CXL 3.2 Mode
 - Cached HBM-DDR mode
- Fabric Management Software
 - Statically or dynamically allocate memory to each XPU and/or CPU based on job needs





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ThankYou